

AMENDMENTS TO THE SPECIFICATION

***Please replace paragraph [0125] with the following amended paragraph:
[0125]:***

Referring first to FIG. 6, an interlayer insulating layer 100 and a contact plug ~~155~~ 115 extending at a depth within the surface of the layer 100 are formed over a substrate (not shown) by known processes. An etch stop layer 120 is then formed over the layer 100 and plug ~~155~~ 115. Lower and upper mold layers 130 and 135 are then successively formed over the etch stop 120 as shown.